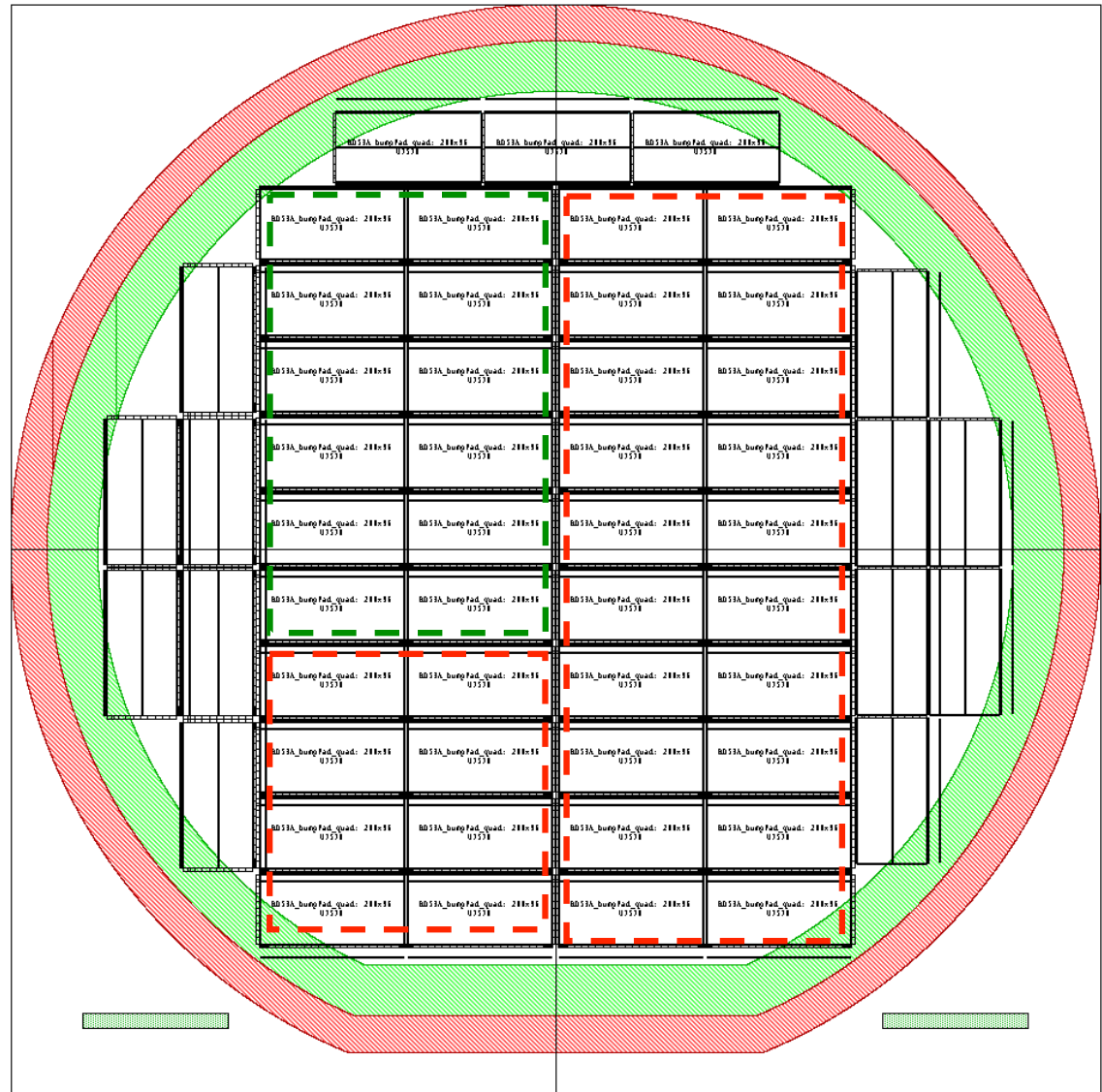
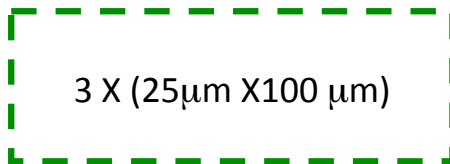


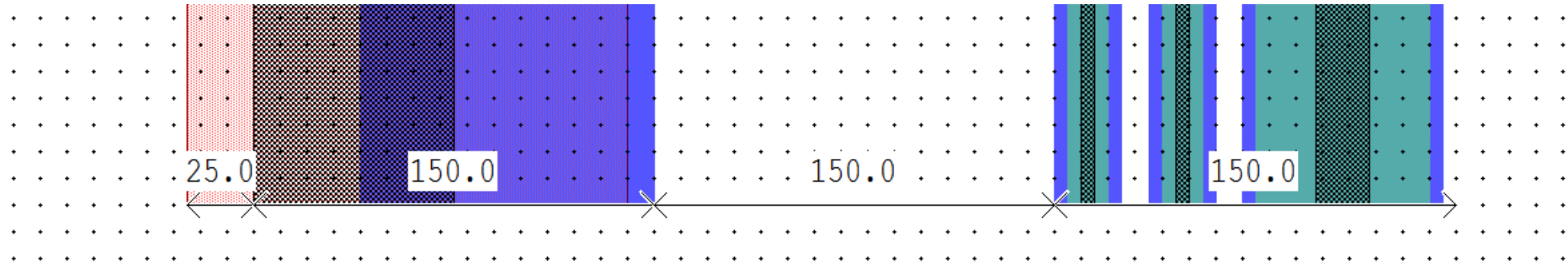
Wafer Assembly: dynamic pairing of adjacent doublets

2x10 DOUBLE CHIPS in the inner area
(equal to 10 QUAD CHIPS)

15 SINGLE CHIPS in the top and in the sides
(eventually more DOUBLE CHIPS)



450um CMS Termination



- HALF CUT-LINE: 25um
- OHMIC IMPLANT: 140um
- FIELD PLATE: 10um
- NO IMPLANT GAP: 150um (between FIELD PLATES)

- GUARD RINGS:
 - 1 BIAS RING (PT-LINE) + 2 GR
 - GR EXTENSION: 150um (from PIXEL EDGE to last FIELD PLATE)

- TOTAL EXTENSION: 450um + 25um HALF CUT-LINE (if required)

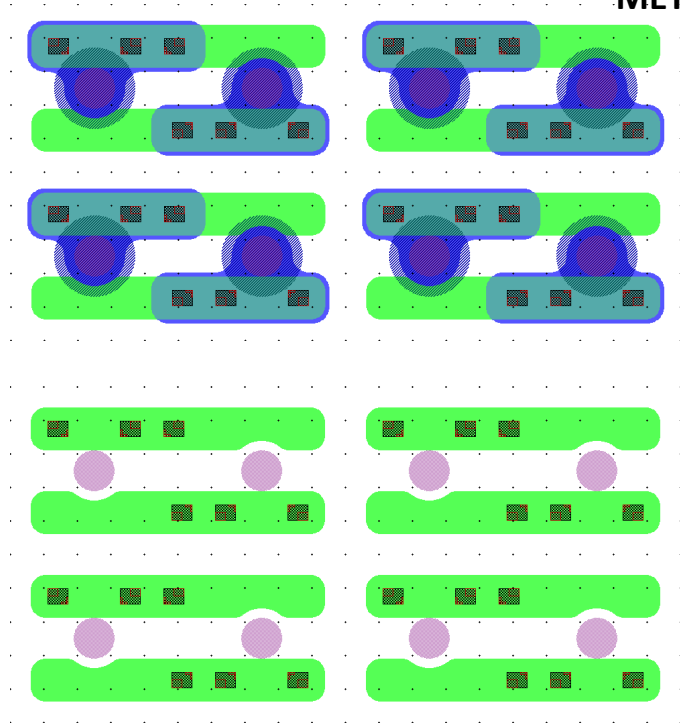
25x100_TM_V1b

PIXEL

«BITE» NO OVERLAP:

N+: 12.5um with BITE

METAL: 3um wider than PASS opening



LONG PIXEL AREA DOUBLE

